

**SPECIFICATION
FOR
LCM MODULE
产品规格书**

MODULE NO.料号: BF7030-02

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Customer Approval 客户确认:

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1. General Specifications 基本规格

No.	Item 项目	Specification 规格	Unit 单位	Remark
1	LCD Size 液晶面板尺寸	7.0	inch	-
2	Panel Type 面板类型	IPS	-	-
3	Resolution 分辨率	1024xRGBx600	Pixel	-
4	Display Mode 显示模式	Normally Black		-
5	Number of Colors 颜色数量	16.7M	-	-
6	Viewing Direction 使用视角	ALL	-	Note1
7	NTSC 色彩饱和度	50%	-	Typ.
8	Contrast Ratio 对比度	500	-	Typ.
9	Luminance 亮度	300	cd/m2	Typ.
10	Module Size 模组尺寸	164.96(H)x100.06(V)x3.49(D)	mm	Note1
11	Panel Active Area 可视区域	154.2144(H)x85.92(V)	mm	Note1
12	Pixel Pitch 像素尺寸	0.0502(H) × 0.143.2(V)	mm	-
13	Pixel Arrangement 像素排列	RGB Vertical stripe		-
14	Weight 重量	TBD	g	-
15	Driver IC 驱动芯片	*EK79007AD3 *EK73217BCGA	-	-
16	Driver IC RAM Size 记忆体		bit	-
17	Light Source 背光源	27LEDS light	-	-
18	Interface 接口方式	MIPI	-	-
19	Operating Temperature 工作温度	-20~+70	℃	-
20	Storage Temperature 存储温度	-30~+80	℃	-

Note 1: Please refer to the mechanical drawing ; 注 1 : 请参照模组图 ;

2. Pin Assignments 接口定义

Pin No.	Symbol 符号	Function 功能描述
1~2	LED+	Backlight anode
3	VGH	Power supply for gate drive output high
4	VGL	Power supply for gate drive output low
5	UPDN	Gate scan direction control
6	SHLR	
7~8	LED-	Backlight cathode
9	AVDD	Analog Power Supply for LCM 系统输入电压
10	GND	Ground
11	MIPI_TDP3	MIPI DSI data lane1+
12	MIPI_TDN3	MIPI DSI data lane1-
13	GND	Ground
14	MIPI_TDP2	MIPI DSI data lane1+
15	MIPI_TDN2	MIPI DSI data lane1-
16	GND	Ground
17	MIPI_TCP	MIPI DSI data lane+
18	MIPI_TCN	MIPI DSI data lane-
19	GND	Ground
20	MIPI_TDP1	MIPI DSI data lane1+
21	MIPI_TDN1	MIPI DSI data lane1-
22	GND	Ground
23	MIPI_TDP0	MIPI DSI data lane0+
24	MIPI_TDN0	MIPI DSI data lane0-
25	GND	Ground
26	STBYB	
27	RST	Chip reset signal 复位
28~29	VDD	Analog Power Supply for LCM 系统输入电压
30	VCOM	VCOM output

3. Electrical Specification 电气特性

3.1 Absolute Maximum Ratings 极限参数

Item 项目	Symbol	Value	Unit	Remark
Analog Power Supply Voltage 模拟供电电压	VDD	-0.3~+4.6	V	-
Logic Input Voltage Range	VIN	-0.3~VDDI+0.3	V	-
Logic Output Voltage Range	VO	-0.3~VDDI+0.3	V	-

3.2 Typical Operation Conditions 典型工作条件

Item 项目	Symbol	Min.最小	Typ.典型	Max.最大	Unit
Supply Voltage 供电电压	VDD	3.0	3.3	3.6	V
NVM Supply Voltage	VPP	7.4	7.5	7.6	V
Power For Analog Circuit	AVDD	-	9.6	-	V
TFT Gate ON Voltage	VGH	-	18	-	V
TFT Gate OFF Voltage	VGL	-	-6	-	V
TFT Common Electrode VoltageE	VCOM	-	3.2	-	V
Input High Voltage 输入高电平	V _{IH}	0.7*VDD	-	VDD	V
Input Low Voltage 输入低电平	V _{IL}	DGND	-	0.3*VDD	V
Output High Voltage 输出高电平	V _{OH}	VDD-0.4	-	VDD	V
Output Low Voltage 输出低电平	V _{OL}	DGND	-	DGND+0.4	V

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3.3 Backlight Circuit Characteristics 背光功耗

Item	Symbol	Min.	Typ.	Max.	Unit
LED Current 背光电流	I_B		140	-	mA
LED Voltage 背光电压	V_f		9		V
Power Consumption 功耗	P_{BL}	-		-	mW

3.4 LCD Current Consumption 液晶面板功耗

Item	Symbol	Typ.	Max.	Unit
Full Mode 正常模式	VCI	-	-	mA
测试条件：VCI=2.8V，IOVCC=2.8V； Interface 驱动类型：行翻转或者列翻转； TN Type=>All Black Pattern. TN型液晶面板=>黑色画面； IPS Type=>All White Pattern. IPS型液晶面板=>白色画面； Temperature：25℃；温度：室温25摄氏度；				
Sleep Mode 休眠模式	VCI	-	-	uA
测试条件：VCI=2.8V，IOVCC=2.8V； DC/DC converter is enabled. Internal oscillator is started and panel scanning is started. 除IC内部晶振和面板扫描外，其他功能都暂停工作； Temperature：25℃；温度：室温25摄氏度；				

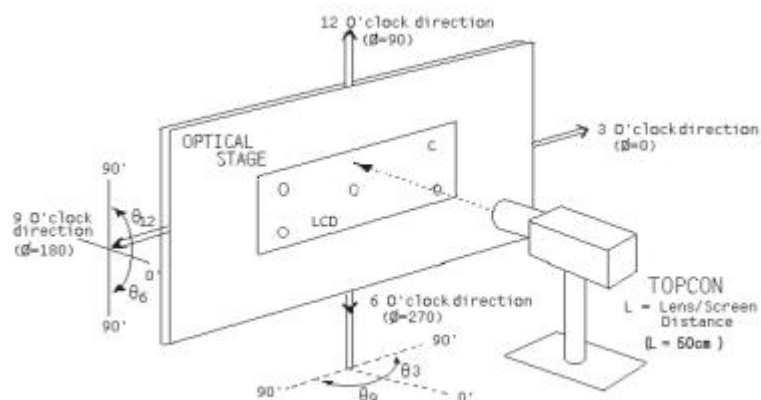
4. Optical Specification 光学参数

4.1 LCM Optical Characteristics 液晶模组光学特性

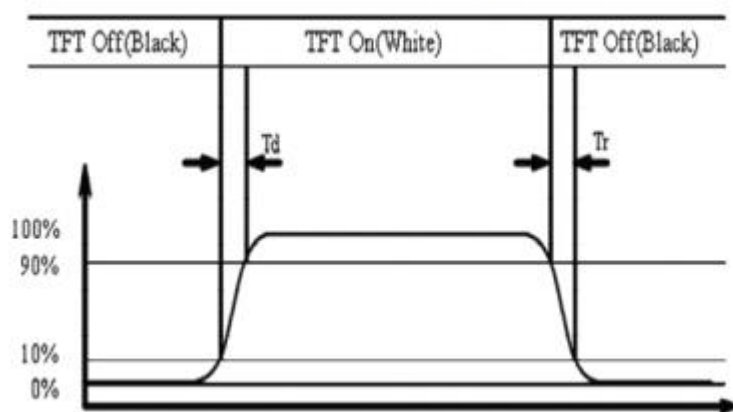
Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Viewing Angle range	Horizontal	Θ_3	CR > 10	-	85	-	Deg.	WV-Pol Note 1
		Θ_9		-	85	-	Deg.	
	Vertical	Θ_{12}		-	85	-	Deg.	
		Θ_6		-	85	-	Deg.	
Luminance Contrast ratio		CR	$\Theta = 0^\circ$	-	800	-		Note 2
Cell Transmittance		Tr		4.8	5.0	-	%	Base on C Light Note 3
White Chromaticity		x_w		TYP. - 0.03	0.308	TYP. + 0.03		Note 4 Base on C Light
		y_w			0.336			
Reproduction of color (C light)	Red	R_x			0.599			
		R_y			0.338			
	Green	G_x			0.299			
		G_y			0.550			
	Blue	B_x			0.139			
		B_y			0.131			
Color Gamut (C light)					-	50	-	%
Response Time (Rising + Falling)		T_{RT}	Ta= 25° C $\Theta = 0^\circ$	-	30	40	ms	Note 5

4.2 Measurement system 测量系统

4.2.1 LCM Viewing Angle



4.2.2 Response time

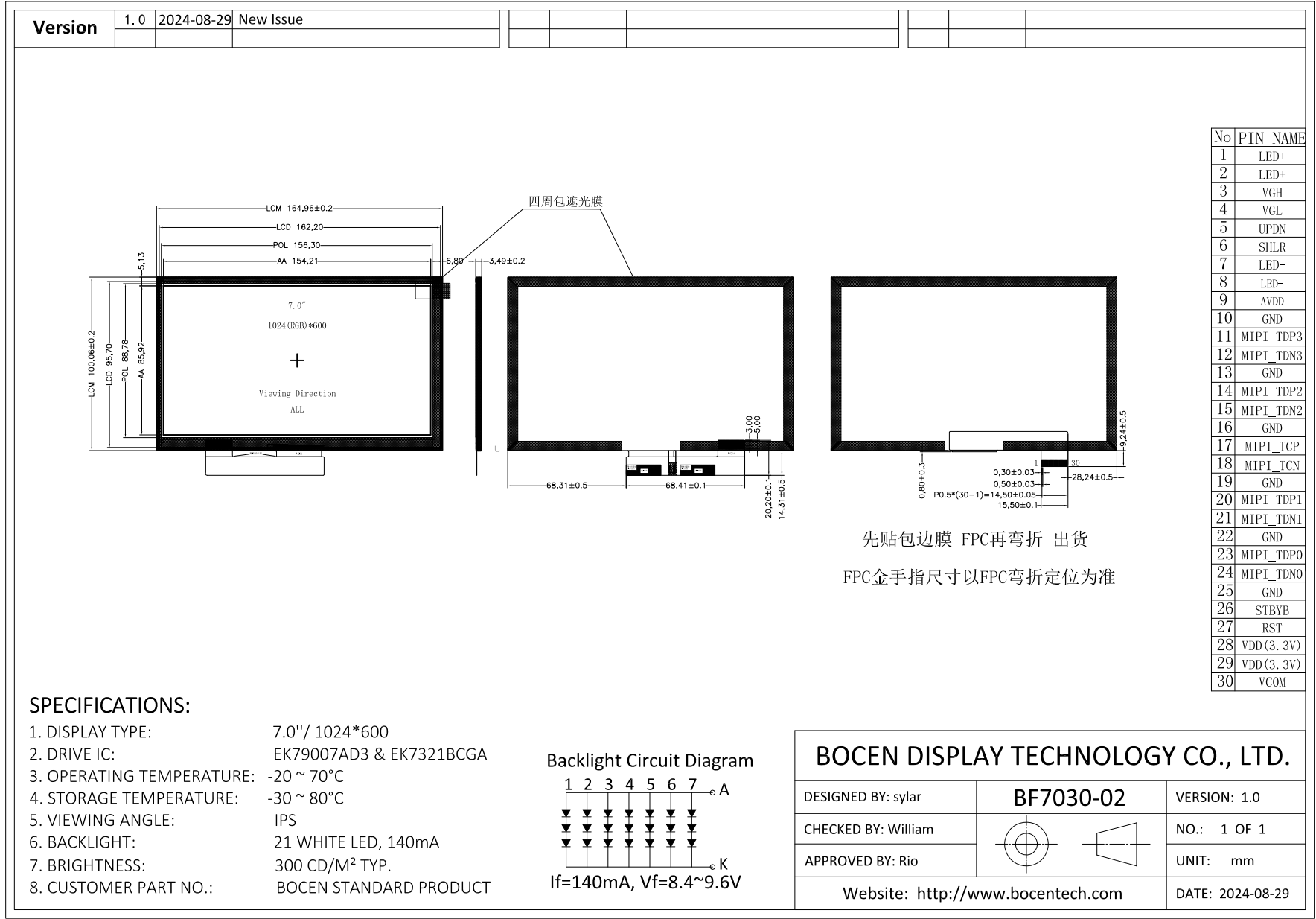


2.3 Contrast Ratio (CR)

Contrast Ratio (CR) is defined mathematically as:

$$CR = \frac{\text{Luminance when displaying a white raster}}{\text{Luminance when displaying a black raster}}$$

5. Mechanical Drawing 模组图



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6. Reliability Test Items 可靠性测试项目

Test Item 测试项目	Test Condition 测试条件	Test result determinant gist 实验结果判定
High temperature storage 高温存储	80±3°C , 24H ;	Inspection after 2~4hours storage at room temperature, the sample shall be free from defects: 试验结束后,已测试的LCD样品必须在室内正常温湿度环境下放置2~4个小时以上才能进行功能和外观检查 , 样品不允许有以下缺陷 : 1.Air bubble in the LCD; 模块中有气泡 ; 2.Non-display; 不显示 ; 3.Glass crack; 玻璃破碎 ; 4. The electrical characteristics requirements shall be satisfied. 需要满足模块电气性能。
Low temperature storage 低温存储	-30±3°C , 24H ;	
High temperature operation 高温运行测试	70±3°C , 24H ;	
Low temperature operation 低温运行测试	-20±3°C , 24H ;	
High temperature /humidity 高温高湿	60°C±3°C,90%±3%RH , 24H ;	
Thermal Shock 冷热冲击	-30°C/0.5h~+80°C/0.5h for a total 24 cycles ;	
Vibration Test 振动测试	Frequency 10Hz~55Hz~10Hz Amplitude : 1.5mm, X , Y , Z direction for total 1H ; (Packing condition)	
ESD test 静电测试	±2KV, Human Body Mode, 150pF/330Ω ; ±8KV, Air Mode, 150pF/330Ω ;	

Remark: 注意 :

1. The test samples should be applied to only one test item.

每个被测试的模块只能用于其中的一个测试项目。

2. Sample size for each test item is 2pcs.

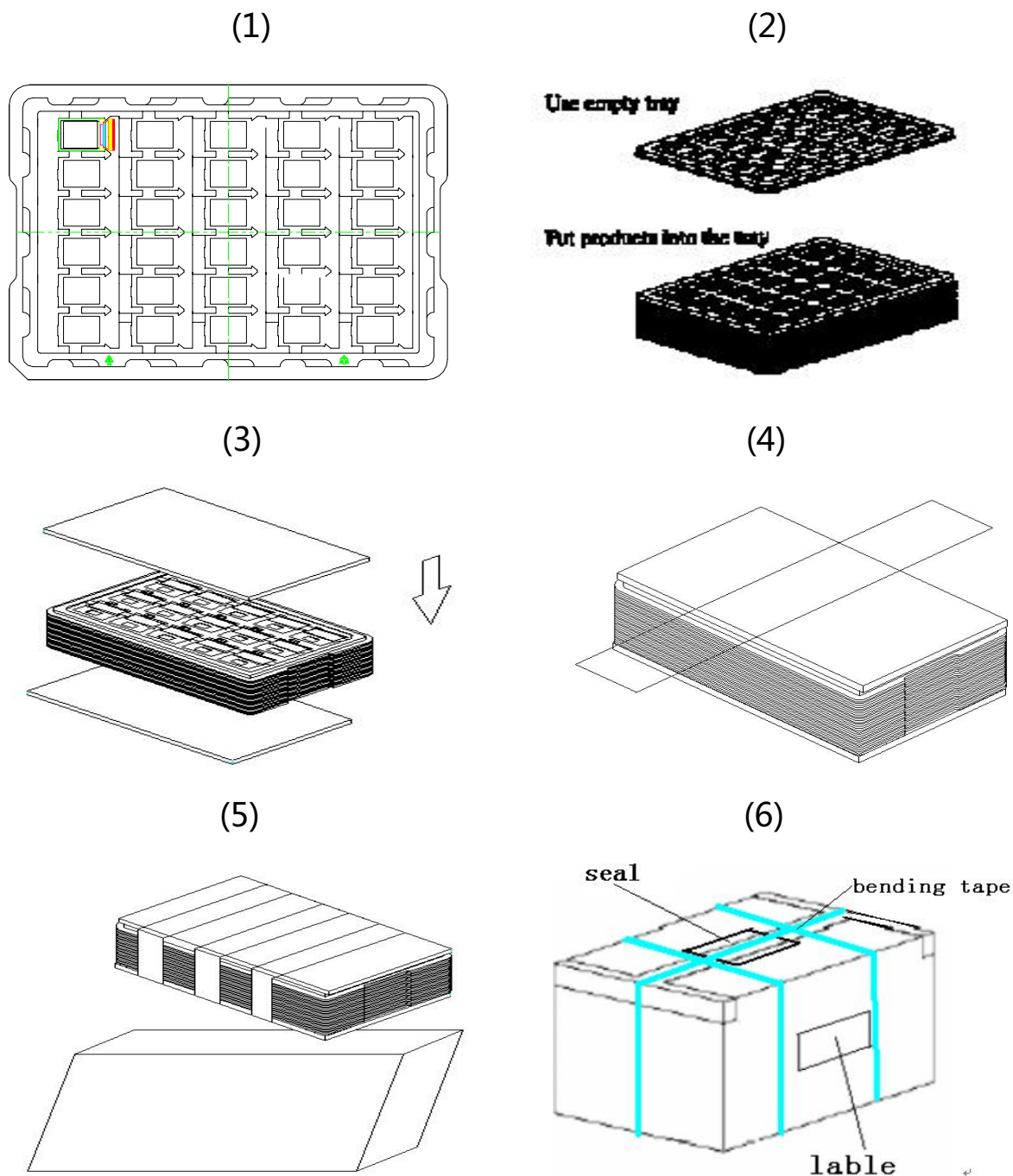
每个测试项目的样品数量为2片。

3. Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic,
Optical Characteristic.

故障判断标准:基本规格,电气特性,机械特性,光电特性。

7. Packing and Storage Specification(Reference Only)包装存储

7.1 Packing Method 包装方法



1. Put module into tray cavity. 把模块放进托盘.

2. Tray stacking. 托盘叠装.

3. Put 1 foam under the tray stack and 1 foam above. 在托盘上下放卡板.
4. Fix the cardboard to the tray stack with adhesive tape. 绑胶带.
5. Put the tray stack into carton. 把邦好的托盘放进纸箱.
6. Carton sealing with adhesive tape. 封纸箱.

7.2 Storage Method 存储方法

- 1.Store in an ambient temperature of $23^{\circ}\text{C}\pm 5^{\circ}\text{C}$, and in a relative humidity of $55\%\pm 15\%$. Don't exceed 12 months and expose to sunlight or fluorescent light.

存储环境温度为 $23\pm 5^{\circ}\text{C}$, 相对湿度为 $55\%\pm 15\%$, 存储不能超过 12 个月 , 不要长时间暴晒。

2. Store in a clean environment, free from dust, active gas, and solvent.

存储在一个干净的环境 , 不受灰尘 , 活性气体和溶剂污染。

3. Store in antistatic container.

存储在防静电环境。

8. Announcements 注意事项

- 1.Do not attempt to disassemble or process the LCD module.

请勿拆卸液晶显示模块。

- 2.Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.

不要在印制电路板上钻额外的孔 , 修改形状或更改印制线路板上元件的位置。

- 3.Except for soldering the interface, do not make any alterations or modifications with a soldering iron; Ensure welding temperature at 320°C to 350°C , the welding time

control within the 10 s, welding note don't stay too long in the same place to avoid scald FPC.

除焊接接口外，不要用烙铁做任何更改；焊接温度保证在 320°C-350°C，焊接时间控制在 10S 以内，焊接时注意不要在同一处停留时间太久以免烫伤 FPC。

4. Other matters in not clear before use, please contact our staff to guide.

其他事项在不清楚使用之前，请联系我司人员指导进行。

-END-